

## Bias Resistor Transistor

### NPN Silicon Surface Mount Transistor with Monolithic Bias Resistor Network

- Applications

Inverter, Interface, Driver

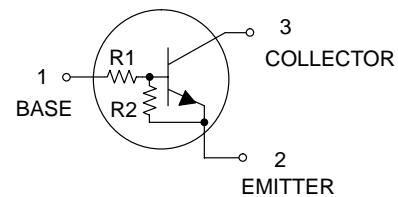
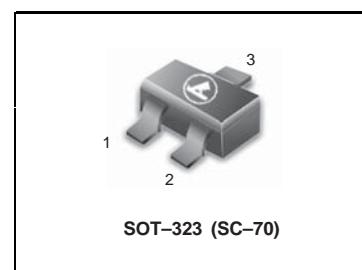
- Features

- 1) Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see equivalent circuit).
  - 2) The bias resistors consist of thin-film resistors with complete isolation to allow positive biasing of the input. They also have the advantage of almost completely eliminating parasitic effects.
  - 3) Only the on/off conditions need to be set for operation, making the device design easy.
- We declare that the material of product compliance with RoHS requirements.
  - S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

- **Absolute maximum ratings (Ta=25°C)**

Parameter	Symbol	Limits		Unit
Supply voltage	V <sub>CC</sub>	50		V
Input voltage	V <sub>IN</sub>	-5 to +10		V
Output current	I <sub>C</sub>	500		mA
Power dissipation	P <sub>D</sub>	200		mW
Junction temperature	T <sub>J</sub>	150		°C
Storage temperature	T <sub>STG</sub>	-55 to +150		°C

**LDTD113ZWT1G  
S-LDTD113ZWT1G**



#### DEVICE MARKING AND RESISTOR VALUES

Device	Marking	R1 (K)	R2 (K)	Shipping
LDTD113ZWT1G S-LDTD113ZWT1G	E8	1	10	3000/Tape & Reel
LDTD113ZWT3G S-LDTD113ZWT3G	E8	1	10	10000/Tape & Reel

- **Electrical characteristics (Ta=25°C)**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Input voltage	V <sub>I(off)</sub>	—	—	0.3	V	V <sub>CC</sub> =5V, I <sub>O</sub> =100μA
	V <sub>I(on)</sub>	1.5	—	—		V <sub>O</sub> =0.3V, I <sub>O</sub> =20mA
Output voltage	V <sub>O(on)</sub>	—	0.1	0.3	V	I <sub>O</sub> /I <sub>l</sub> =50mA/2.5mA
Input current	I <sub>I</sub>	—	—	7.2	mA	V <sub>I</sub> =5V
Output current	I <sub>O(off)</sub>	—	—	0.5	μA	V <sub>CC</sub> =50V, V <sub>I</sub> =0V
DC current gain	G <sub>I</sub>	82	—	—	—	V <sub>O</sub> =5V, I <sub>O</sub> =50mA
Input resistance	R <sub>I</sub>	0.7	1	1.3	kΩ	—
Resistance ratio	R <sub>2</sub> /R <sub>1</sub>	8	10	12	—	—
Transition frequency	f <sub>r</sub> *	—	200	—	MHz	V <sub>CE</sub> =10V, I <sub>E</sub> =-50mA, f=100MHz

\* Characteristics of built-in transistor

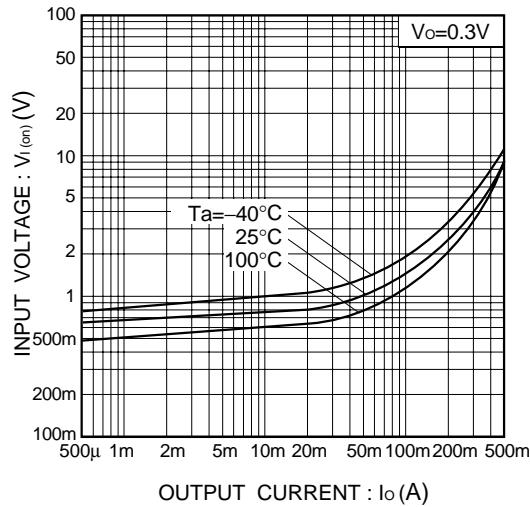
**LDTD113ZWT1G;S-LDTD113ZWT1G**
**●Electrical characteristic curves**


Fig.1 Input voltage vs. output current  
(ON characteristics)

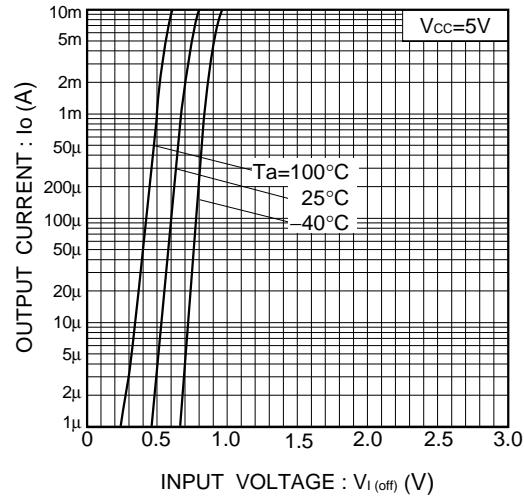


Fig.2 Output current vs. input voltage  
(OFF characteristics)

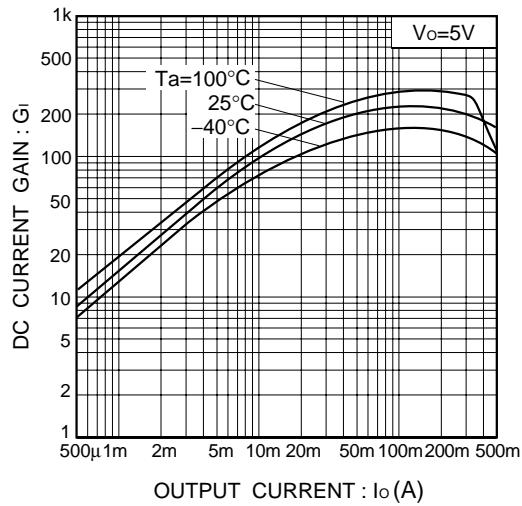


Fig.3 DC current gain vs. output current

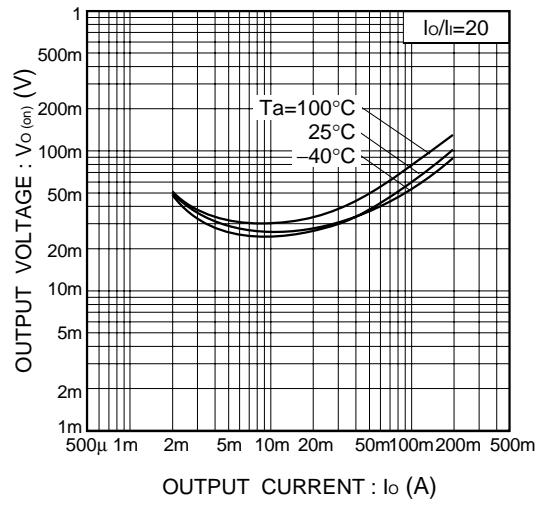
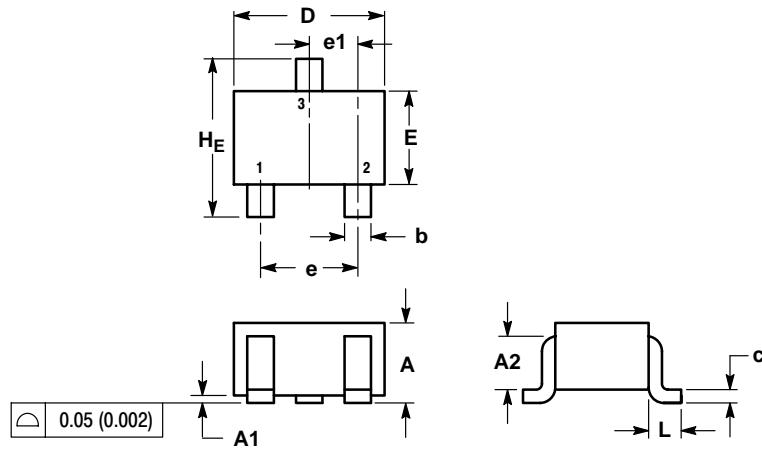
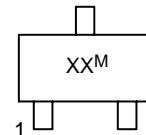


Fig.4 Output voltage vs. output current

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**SC-70 (SOT-323)**


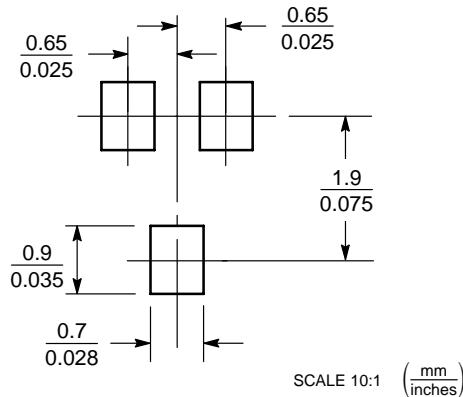
NOTES:  
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
 2. CONTROLLING DIMENSION: INCH.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.7	REF		0.028	REF	
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
e	1.20	1.30	1.40	0.047	0.051	0.055
e <sub>1</sub>	0.65	BSC		0.026	BSC	
L	0.425	REF		0.017	REF	
H <sub>E</sub>	2.00	2.10	2.40	0.079	0.083	0.095

**GENERIC  
MARKING DIAGRAM**


XX = Specific Device Code  
 M = Date Code  
 □ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.  
 Pb-Free indicator, "G" or microdot "■", may or may not be present.

**SOLDERING FOOTPRINT\***


SCALE 10:1 (mm/inches)